

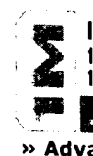
Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1986294	(wafer\$1 or semiconductor\$1 or chip\$1 or substrate\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:28
L2	0	1 and (detect\$3 or determine)same(plurality or plural)same (leads\$1 or terminal\$1)same laterally near3 extent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:41
L3	85	1 and (detect\$3 or determine)and(plurality or plural)and(leads\$1 or terminal\$1)and laterally near3 extent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:42
L4	44	1 and (detect\$3 or determine)and(plurality or plural)and(leads\$1 or terminal\$1)and laterally near3 extent\$3 and coplanarity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:43
L5	44	4 and (ccd or camera or sensor\$1 or detector\$1 or sens\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:46

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership Publications/Services Standards Conferences Careers/Jobs

**IEEE Xplore®**  
 RELEASE 1.8

 Welcome  
 United States Patent and Trademark Office

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)
[Quick Links](#)

Welcome to IEEE Xplore®

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

## Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

## Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced
- ☐ CrossRef

## Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

## IEEE Enterprise

- ☐ Access the IEEE Enterprise File Cabinet

Try our New Full-text Search Prototype **GO**[Help](#)

- 1) Enter a single keyword, phrase, or Boolean expression.  
Example: acoustic imaging (means the phrase acoustic imaging plus any stem variations)
- 2) Limit your search by using search operators and field codes, if desired.  
Example: optical <and> (fiber <or> fibre) <in> ti
- 3) Limit the results by selecting Search Options.
- 4) Click Search. See [Search Examples](#)

(wafer or semiconductor or chip or substrate)and (detect or determine) and coplanarity

**Start Search****Clear**

Note: This function returns plural and suffixed forms of the keyword(s).

 Search operators: <and> <or> <not> <in> [More](#)

 Field codes: au (author), ti (title), ab (abstract), jn (publication name), de (index term) [More](#)

## Search Options:

## Select publication types:

- ☒ IEEE Journals
- ☒ IEE Journals
- ☒ IEEE Conference proceedings
- ☒ IEE Conference proceedings
- ☒ IEEE Standards

## Select years to search:

 From year:  to 

## Organize search results by:

 Sort by: 

 In:  order

 List  Results per page

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE



Membership Publications/Services Standards Conferences Careers/Jobs

**IEEE Xplore®**  
 RELEASE 1.8

 Welcome  
 United States Patent and Trademark Office


» Se.

[Help](#) [FAQ](#) [Terms](#) [IEEE Peer Review](#)
[Quick Links](#)

## Welcome to IEEE Xplore®

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

## Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

## Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced
- ☐ CrossRef

## Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

## IEEE Enterprise

- ☐ Access the IEEE Enterprise File Cabinet

 Your search matched **2** of **1108362** documents.

 A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance Descending** order.

## Refine This Search:

You may refine your search by editing the current search expression or entering a new one in the text box.


☐ Check to search within this result set

## Results Key:

**JNL** = Journal or Magazine   **CNF** = Conference   **STD** = Standard

**1 Application of the Taguchi method to chip scale package (CSP) design**  
*Mertol, A.;*

 Advanced Packaging, IEEE Transactions on [see also Components, Packaging Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on], Volume: 23, Issue: 2, May 2000  
 Pages:266 - 276

[\[Abstract\]](#)   [\[PDF Full-Text \(548 KB\)\]](#)   **IEEE JNL**
**2 Warpage study of glob top cavity-up EPBGA packages**
*Dexin Liang;*

 Electronic Components and Technology Conference, 1996. Proceedings., 46th  
 31 May 1996  
 Pages:694 - 701

[\[Abstract\]](#)   [\[PDF Full-Text \(820 KB\)\]](#)   **IEEE CNF**

## Print Format

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved

09/991,909

